



Material Content Data Sheet



Sales Product Name		BSC026NE2LS5		Issued		25. January 2018		
MA#		MA001868664						
Package		PG-TDSON-8-6		Weight*		106.57 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.210	0.20	0.20	1975	1975
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		106	
	non noble metal	iron	7439-89-6	0.038	0.04		355	
	non noble metal	copper	7440-50-8	37.762	35.43	35.48	354332	354793
	non noble metal	copper	7440-50-8	0.022	0.02	0.02	202	202
wire	non noble metal	copper	7440-50-8	0.022	0.02	0.02	202	202
encapsulation	organic material	carbon black	1333-86-4	0.088	0.08		830	
	plastics	epoxy resin	-	6.279	5.89		58920	
	inorganic material	silicondioxide	60676-86-0	37.852	35.51	41.48	355178	414928
leadfinish	non noble metal	tin	7440-31-5	1.452	1.36	1.36	13621	13621
plating	noble metal	silver	7440-22-4	0.166	0.16	0.16	1553	1553
solder	non noble metal	tin	7440-31-5	0.007	0.01		70	
	noble metal	silver	7440-22-4	0.009	0.01		87	
	non noble metal	lead	7439-92-1	0.355	0.33	0.35	3328	3485
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.007	0.01		63	
	non noble metal	iron	7439-89-6	0.022	0.02		209	
	non noble metal	copper	7440-50-8	22.292	20.92	20.95	209171	209443
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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